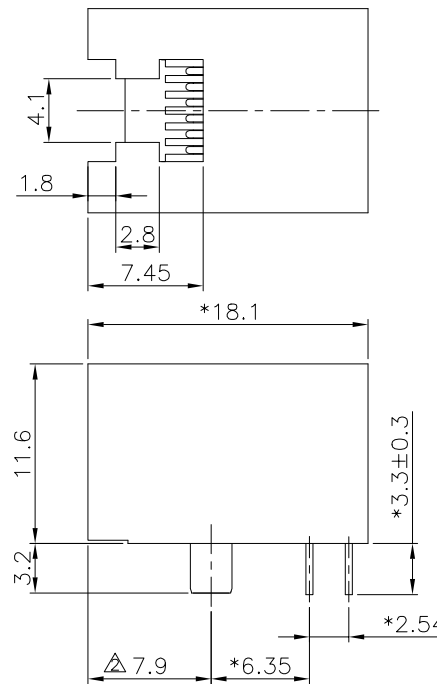
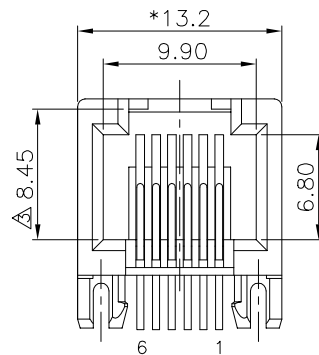


PC Board Layout t=1.60mm  
Component Side Shown



REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
△		DRAWING MODIFY	JACKEY 7/1/99	
△		7.9 was 8.0	JACKEY 7/14/99	H
△		Add P/N	LUSHENG 01/16/01	
△		DRAWING MODIFY	CZH 7/15/02	
△		DRAWING MODIFY	CZH 02/08/03	
△		DRAWING MODIFY	SAMMY 02/02/04	
△		Add P/N	Ying 21/05/04	
△		Add P/N	SHE 7/13/04	G
△		Add P/N	CXG 5/05/05	

NOTES:

ELECTRICAL:

1. VOLTAGE RATING : 150 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 20 MILLIOHMS MAX.
- △ 4. INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
5. DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

1. HOUSING MATERIAL : GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL : PHOSPHOR BRONZE  $\phi$ 0.46mm.
3. PLATING : GOLD PLATING OVER NICKEL.
- △ 4. OPERATING LIFE : 750 CYCLES MIN.
5. PCB RETENTION PRE-SOLDER : 1 LB MIN.
6. PCB RETENTION POST-SOLDER: 10 LBS MIN.

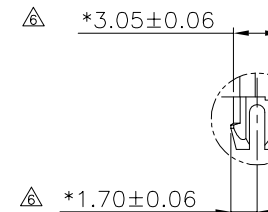
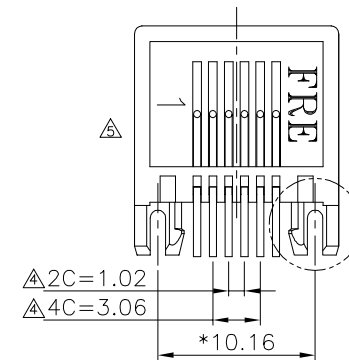
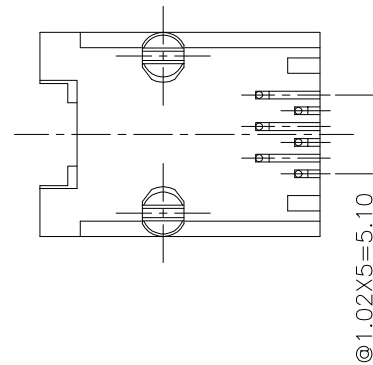
ENVIRONMENTAL:

1. STORAGE : -40°C TO +85°C.
  2. OPERATION: -20°C TO 85°C.
- MATES WITH MODULAR PLUG CONFORMING TO  
FCC PART 68, SUBPART F.  
CUL FILE NO. E163191

PART NUMBER: E536X-300XGX

2- 2C  
4- 4C  
6- 6C

- 1- 3u" 2- 6u" 3-15u"  
4- 30u" 5-50u" F-Glod flash<sup>△</sup>
- △ MATERIAL OF HS'G :  
0- PBT + G.F.BK.  
△ 4-FR50 BK  
△ 5-FR52 BK



DETACHED LISTS	← MM (INCH) →		DFTO BASS	DATE 8/28/98	FULL RISE ELECTRONIC CO., LTD
	TOLERANCES EXCEPT AS NOTED		CHKD	DATE	
			MFO	DATE	
			APPVL XLF	DATE 05/05/05	
MM		±	MATERIAL :		TITLE
.0 ± 0.2		±	QT'Y :		11.5mm SIDE PCB JACK 6P
.00 ± 0.15		±	FINISH :		DRAWING NO. GE533022
.000 ± 0.075		±	SCALE : 3 : 1		/PART NO. SEE NOTE
ANGLES ± 0.5		THIRD ANGLE PROJECTION		DO NOT SCALE DRAWING	SIZE A3
				SHEET 1 OF 1	REV 9